



The LHC beam loss monitoring system's data acquisition card

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AB-BI-BL



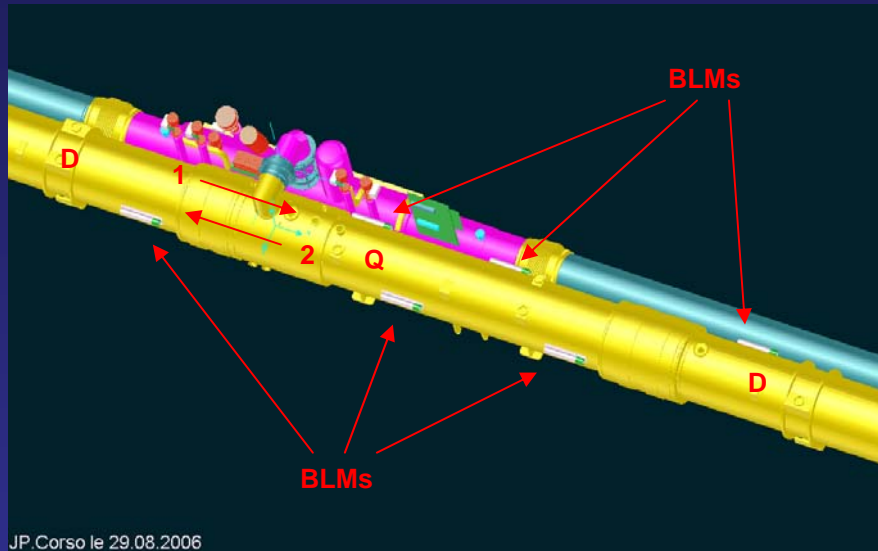
Outline



- Introduction: the BLM System
- Specification of the BLM DAC
- The data acquisition card
- FPGA functionality
- Tests during operation
- Measurement results
- Conclusion
- Acknowledgement



Introduction: the BLM System



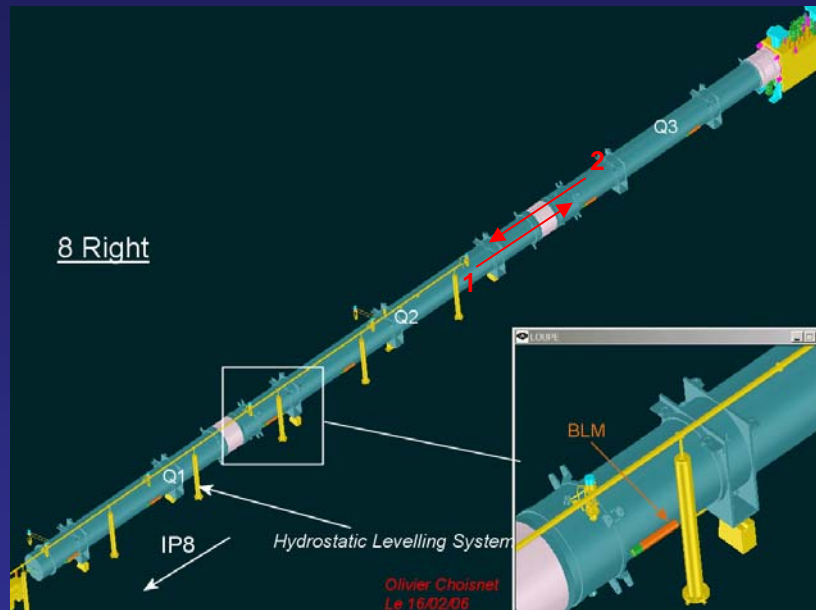
JP.Corso le 29.08.2006

- 3680 Ionization chambers
- 290 Secondary emission monitors
- 650 BLM data acquisition cards
- The cards in the arc are installed underneath the magnets in a 19" crate





Introduction: the BLM System

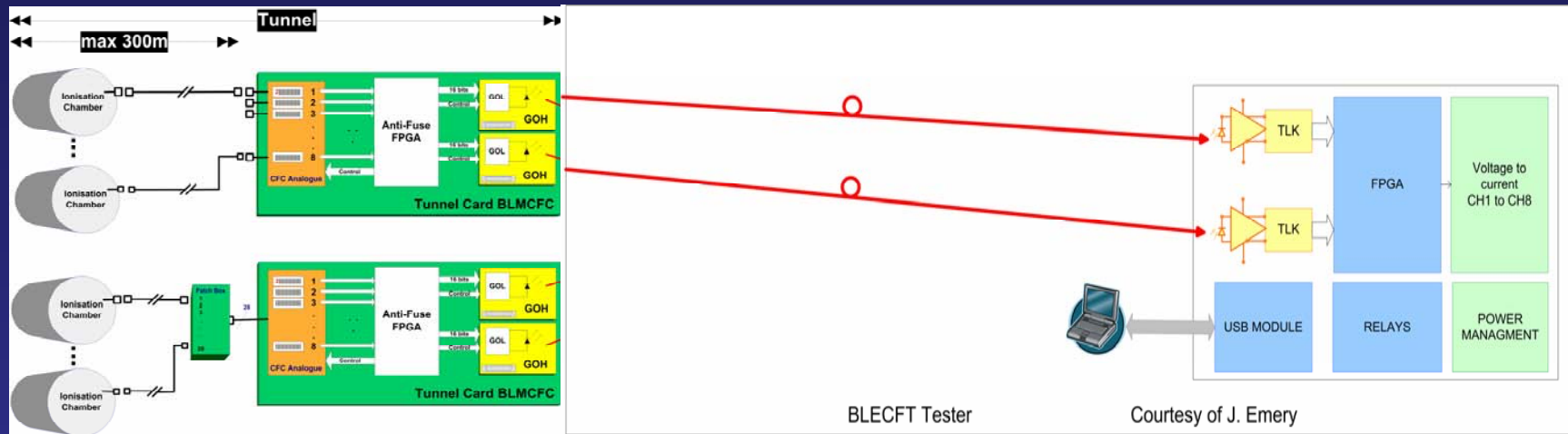


- Electronic cards are installed in the nearby side-tunnels, because of reduced radiation level
- Up to 6 x 19" crates with 10 DACs are installed in the straight section
- Signal cable with length up to 600m





Introduction: the BLM System



- Optical links are connected to 340 threshold comparators (TC) with an optical receiver card on the surface
- 25 VME crates are distributed around the LHC
- Each crate includes a PowerPC (data logging), a Combiner card (connected to the beam interlock system), and two timing cards
- USB connected system for test and development



Specification



- Radiation tolerant up to 500Gy (20 LHC lifetime)
- Reliability level SIL3 (10^{-6} to 10^{-7} failure/h) to protect the equipment of damage
- Current measuring range 2.5pA to 1mA
- Error +/-25% in the range from 1mA to 1nA
- Error +100%/-50% in the range from 1nA to 10pA
- Integration time window 40us



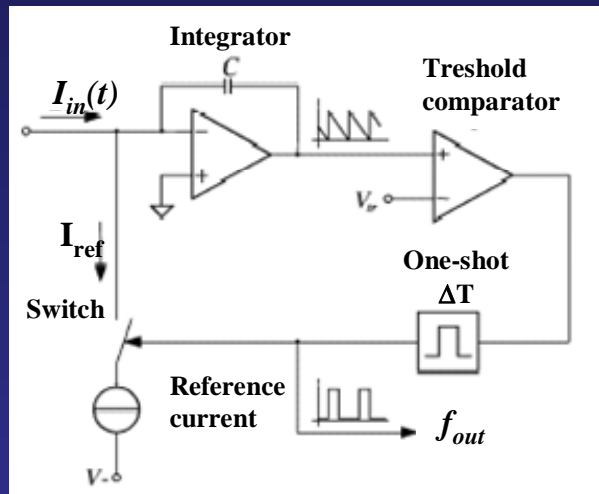
Specification



- Input over-current protection: 10A@100 μ s
- Input over-voltage protection: 1500V@100 μ s
- Redundant optical data transfer to surface
- Test features for system check
- Survey of the card voltage supplies
- Survey of detector high voltage supply



The acquisitions card



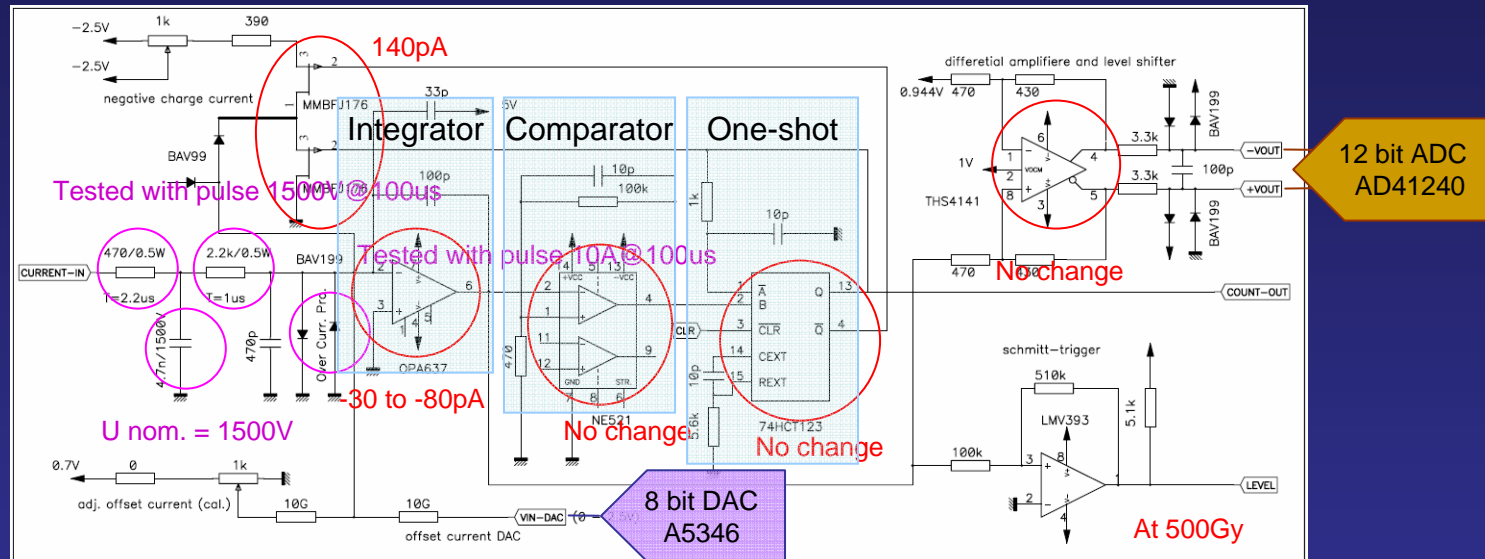
Essentials of the input circuit

- Current to frequency converter (CFC)
- Balanced charge integrator
- No charge loss (“no blind time”)
- Very large dynamic range
- Output frequency depends on input current

Input Current	Output frequency
1mA	5MHz
1uA	5kHz
1nA	5Hz
1pA	5mHz



The acquisitions card

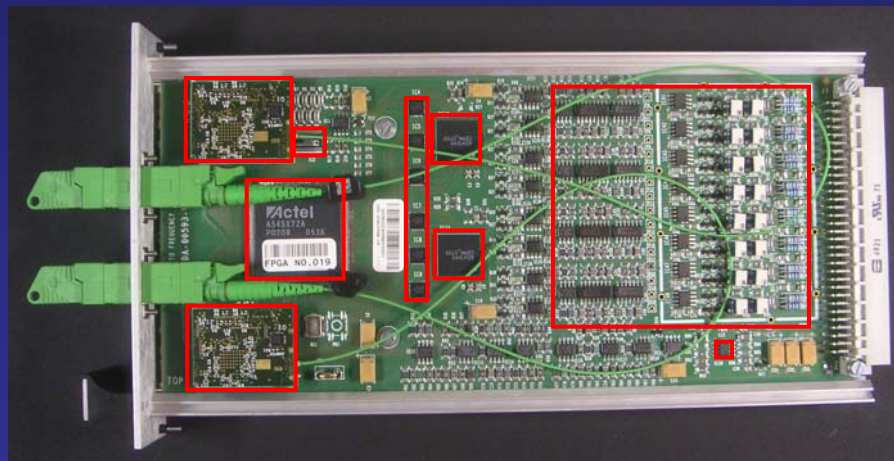


Measures to fulfill the specification

- Irradiation of single components (JFET, OP, Comparator, One shot, ...)
- Insertion of fast protection diodes, high voltage capacitors, and leaded resistors on the input
- ADC added to decrease response time / increase dynamic range
- Automatic feedback loop with DAC to compensate leakage current due to integrated dose



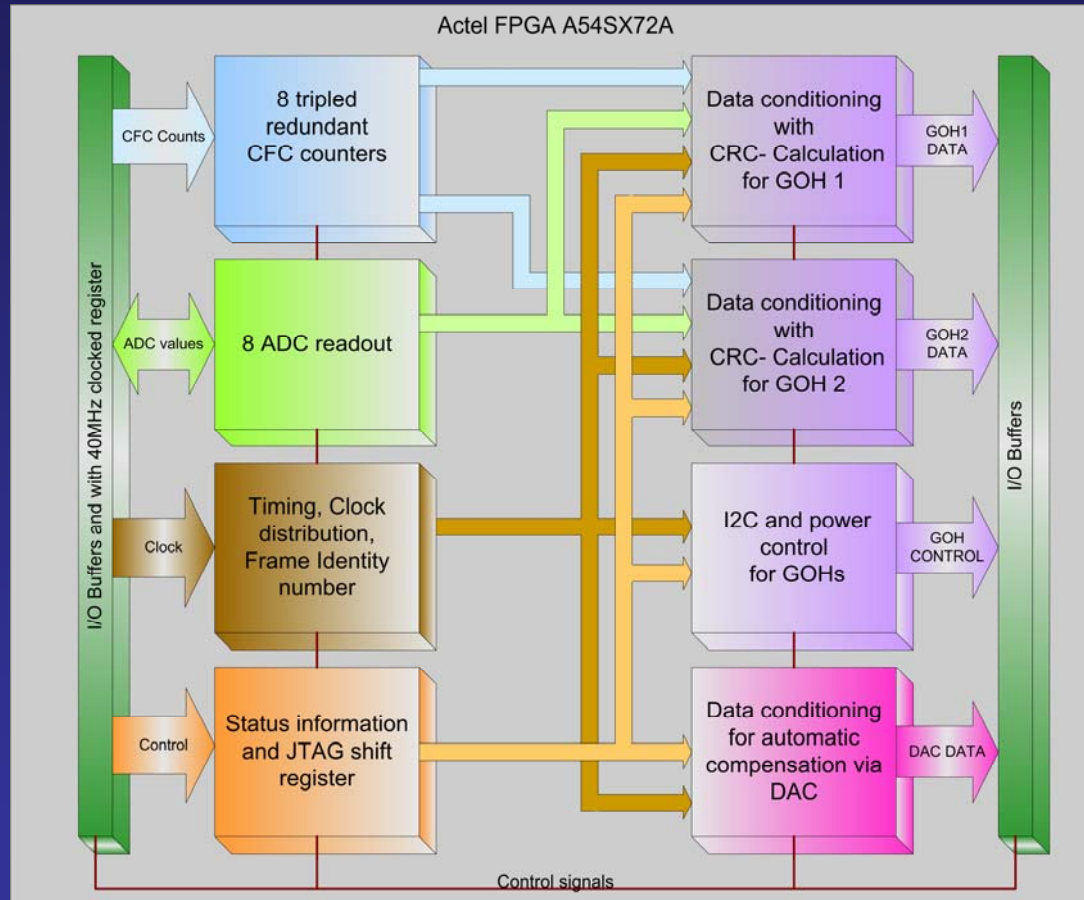
The acquisitions card



- 8 current inputs (CFC)
- ADC AD41240 CERN ASIC
- LM4140 voltage reference
- FPGA for data combination
- Two redundant GOH from CMS (including CERN ASIC)
- Line driver CRT910 CERN ASIC
- DAC AD5346



FPGA functional description



- Actel antifuse FPGA A54SX72A
- 4024 sequential cells
- 2012 combinational cells
- Total logic usage: 85%
- Pin usage: 100%
- 40 MHz clock



Tests during operation



- **Constant 10pA offset current**
 - Check on channel availability
 - In case of exceeding limits, a beam dump can be generated
- **Continuous status monitoring**
 - Monitoring of voltage supplies and other status information
 - Should failure occur, a beam dump can be generated



Tests during operation



- **Continuous check during data transmission**
 - Checked at each transmission
 - * Card identity number check
 - * Frame identity number check
 - * Cycle redundancy check
 - Should failure occur, a beam dump can be generated



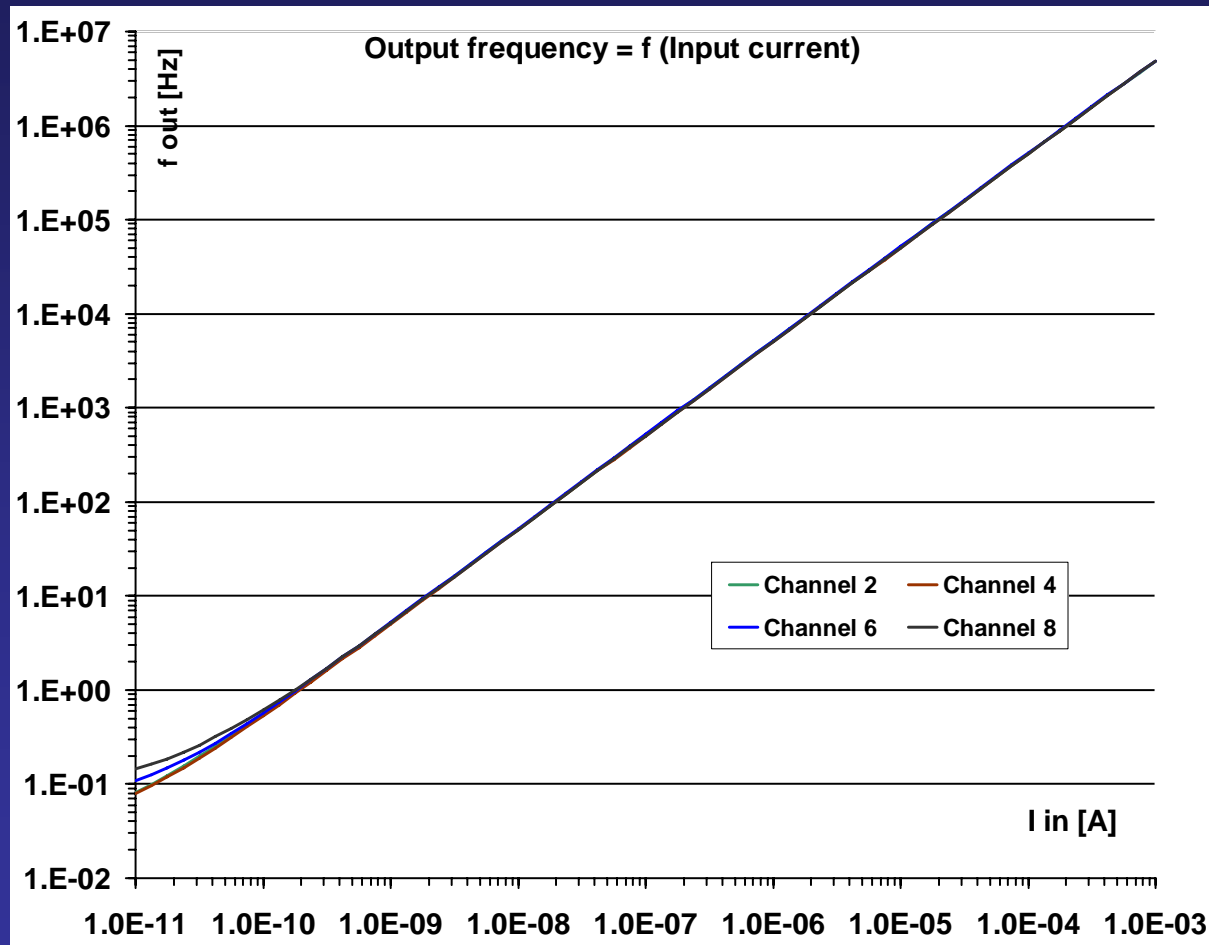
Tests during operation



- **High Voltage (HV) activation test**
 - 100pA added, dynamic test
 - Degradation of electronic can be detected
 - In case limits are exceeded, no beam permission given
 - To be carried out before each beam fill
- **HV modulation test**
 - Capacitive current injection via chamber electrodes
 - Degradation of complete chain can be detected
 - In case limits are exceeded, no beam permission given
 - To be carried out before each beam fill



Measurement results



CFC input circuit

- Dynamic range over 8 decades from 1 mA to 10 pA
- Down to 1 nA max error of 6.5%
- Down to 10 pA max error of 96%



Conclusion



- **Error**

- +/-25% down to 1nA
- +100%/-50% down to 10pA
- improvement possible with accurate calibration

- **Radiation tolerance of 500Gy**

- 74HCT123 (one shot), malfunction at 300 to 350Gy
components recovered when not irradiated
- 54SX72A (FPGA), malfunction at 480 to 790Gy,
no SEU detected up to 1×10^{12} p/cm²
- All other components were working up to 1500Gy

- **Input over current and voltage protection**

- completely fulfilled



Conclusion



- **Survey and test features**
 - All features working correctly
- **Optical link**
 - Radiation tolerant design
 - Installed test system at HERA, no CRC error occurred for several months
- **Extra system test**
 - Temperature test: 0 – 70°C passed
 - Magnetic field test: 1000Gauss passed, performed for CMS



Acknowledgment



- **I would like to thank**
 - K. Kloukinas, P. Moreira, A. Marchioro for providing help with the ASICs from PH/MIC
 - A. Singovski, F. Vasey, R. Rusack for providing help with GOH from CMS
 - The beam loss section
- **Further information can be found:**
 - The LHC Beam Loss Monitoring System's Surface Building Installation (Poster/Paper LECC 2006 from C. Zamantzas)
 - Functional and linearity test system for the LHC beam loss data acquisition card (Poster/Paper LECC 2006 from J. Emery)
 - <http://www.cern.ch/BLM>



Appendix

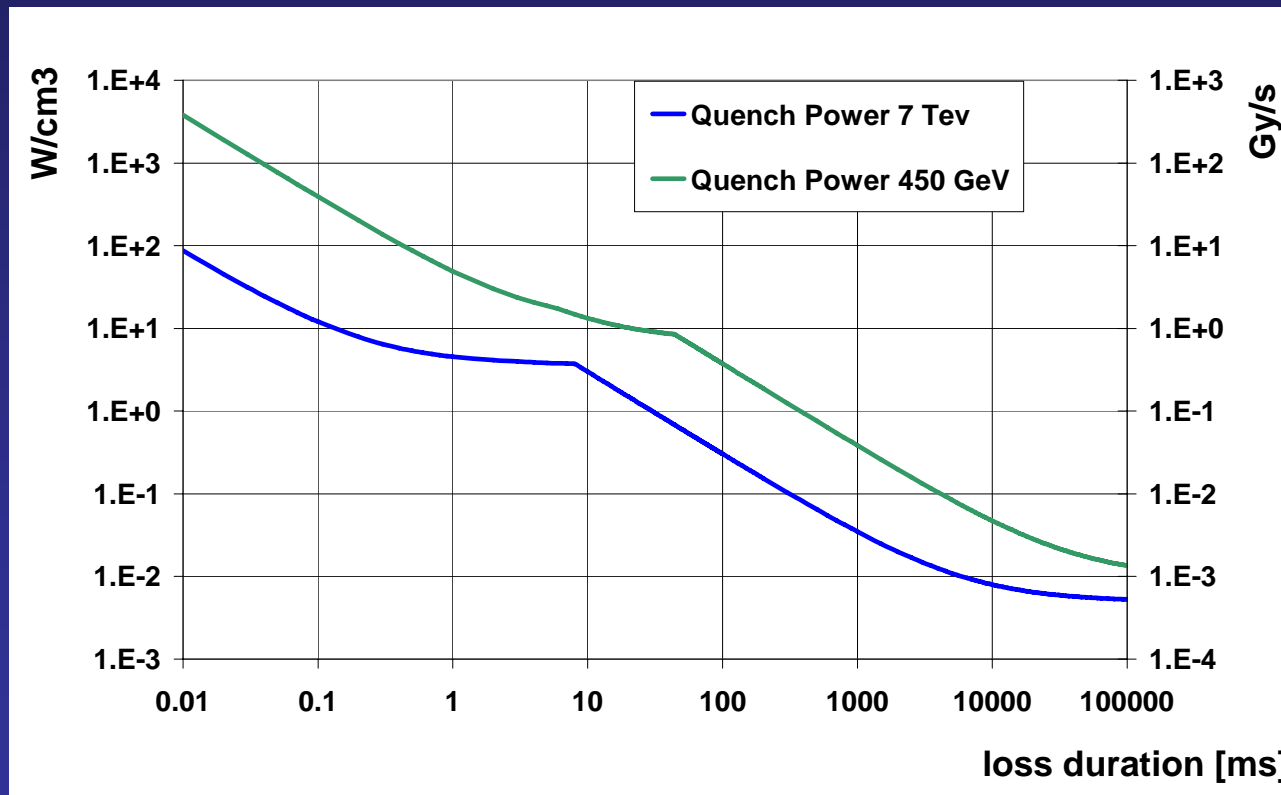




Appendix



- Magnet quench levels

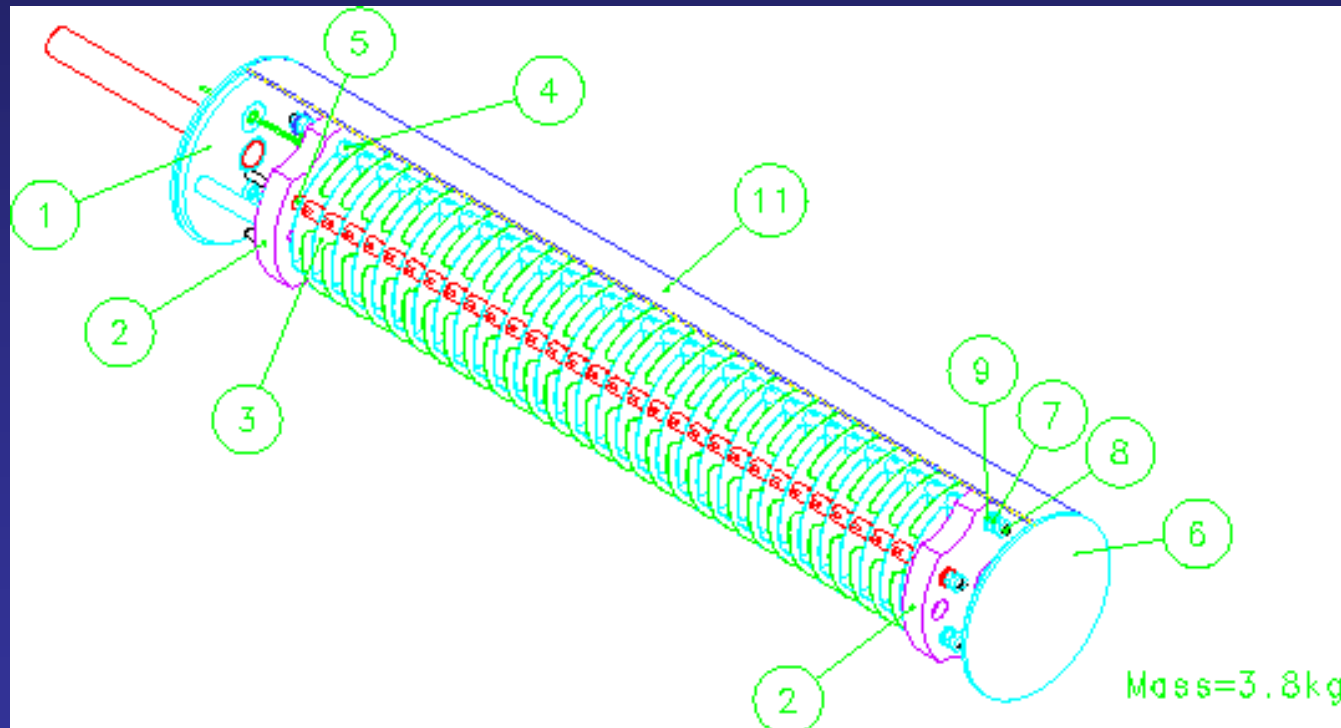




Appendix

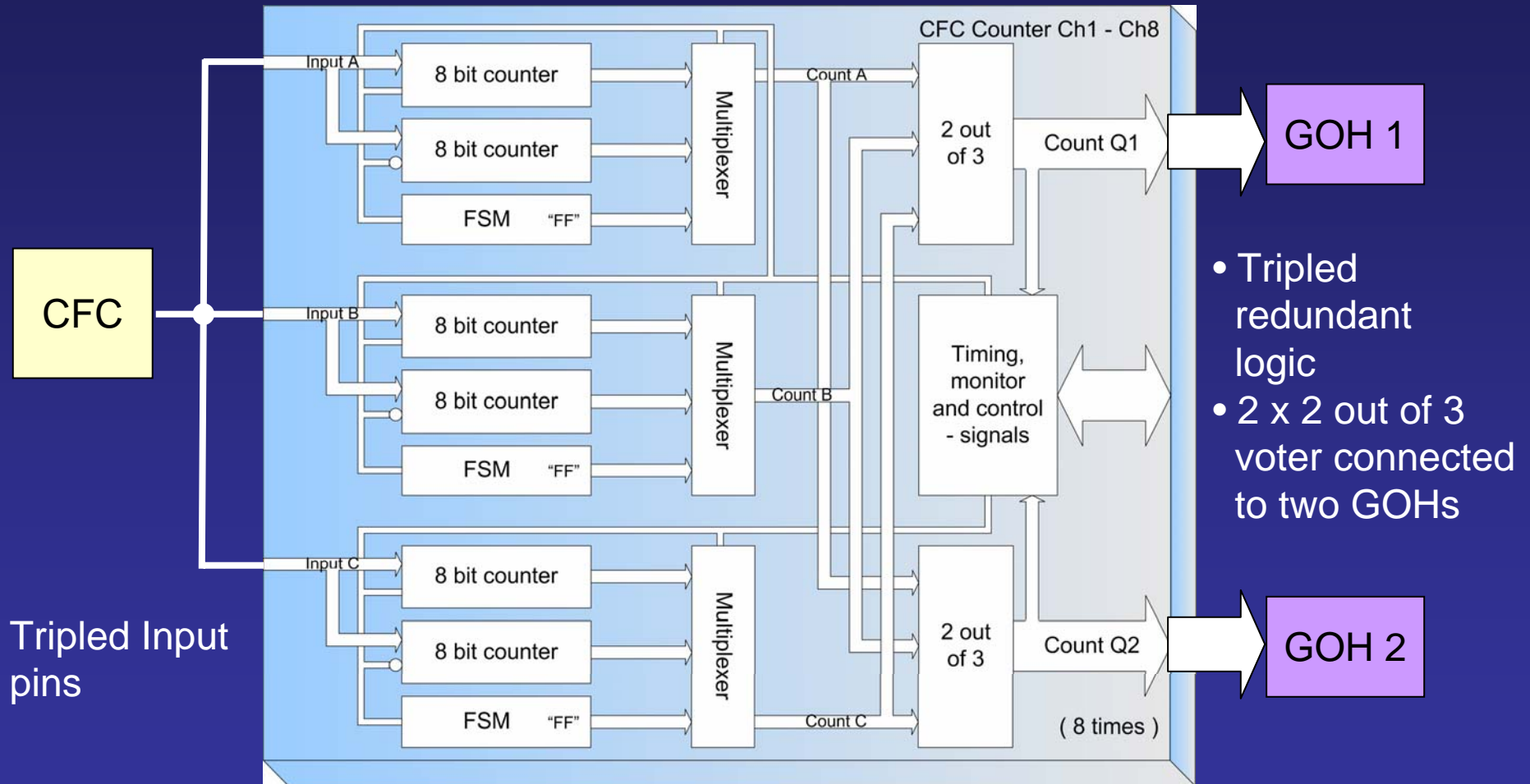


- Ionization chamber



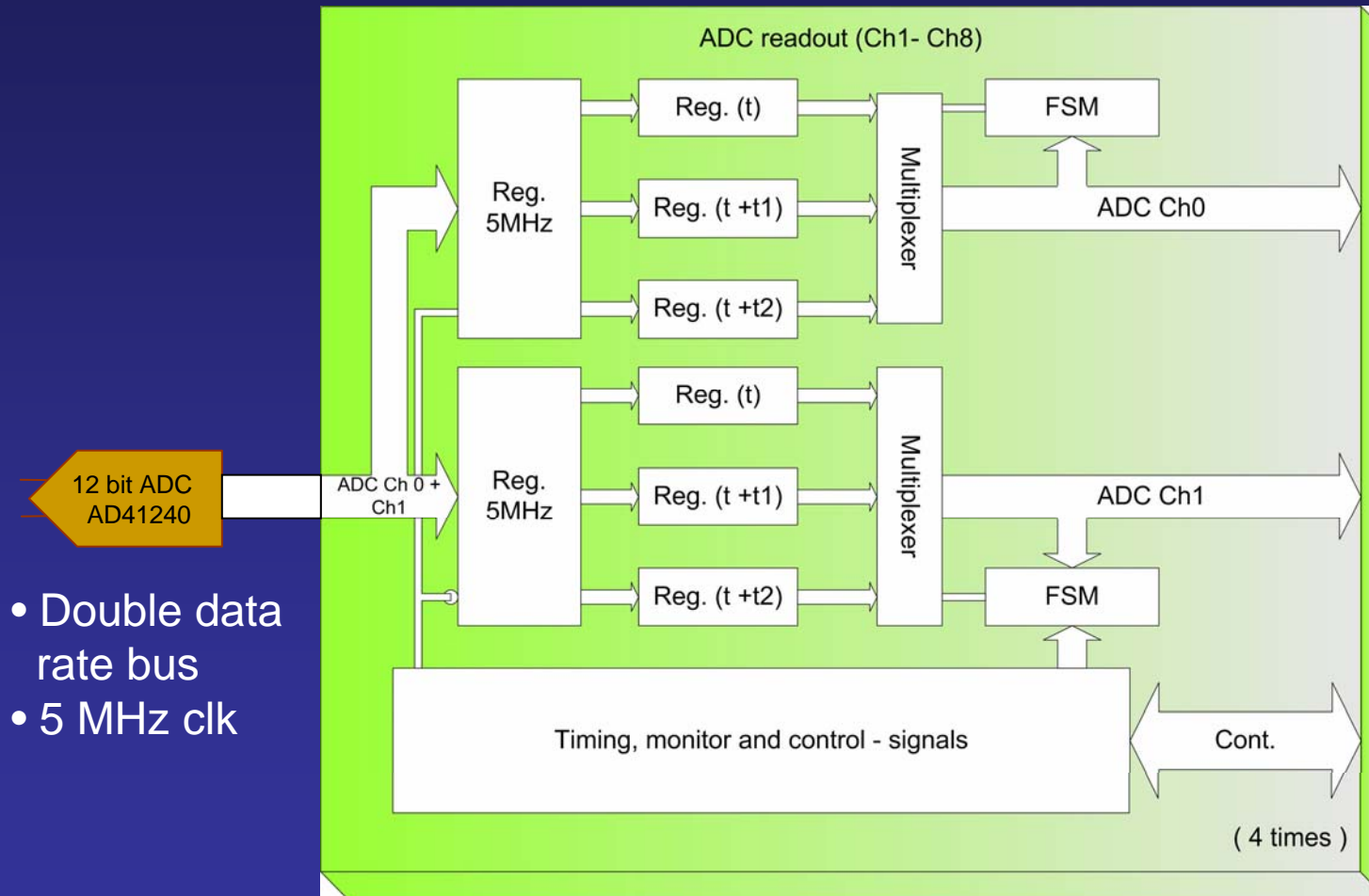


FPGA functional description



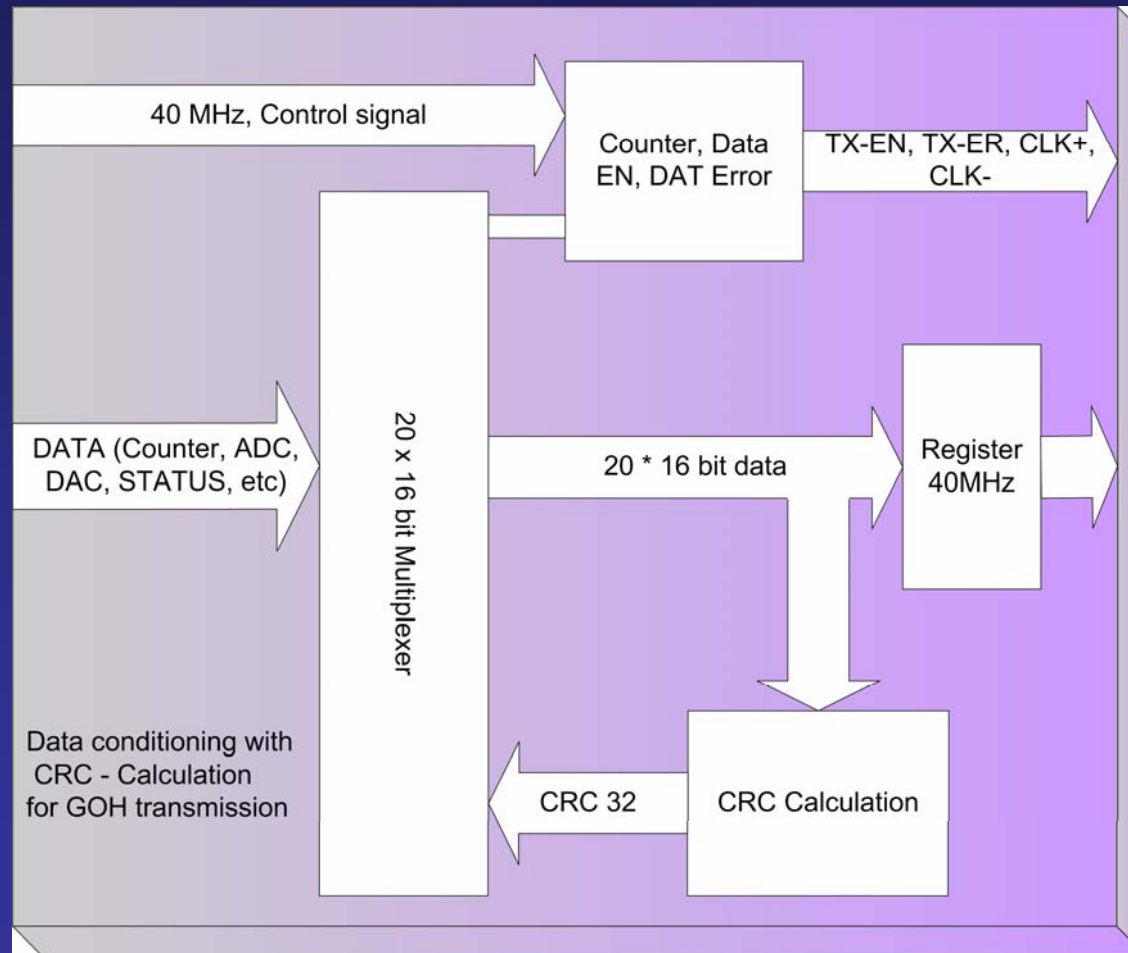


FPGA functional description



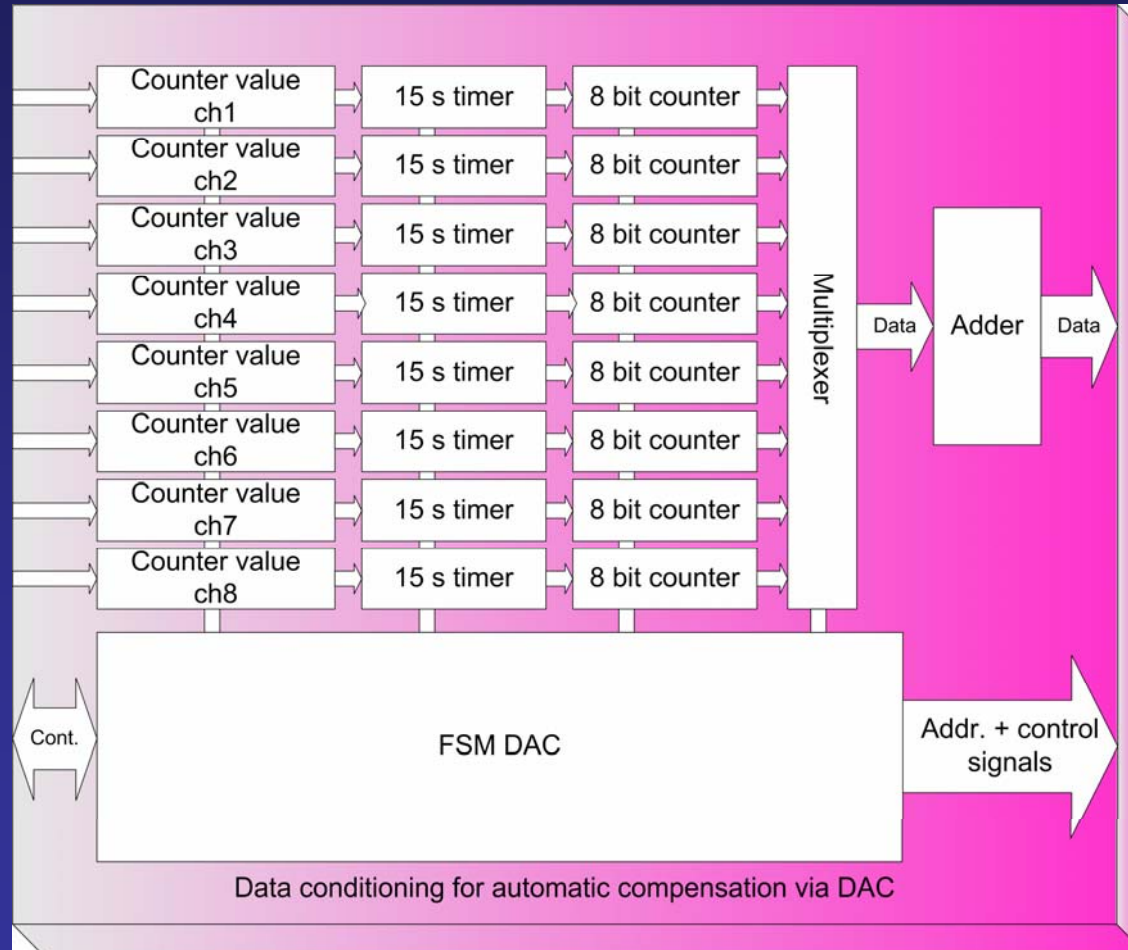


FPGA functional description



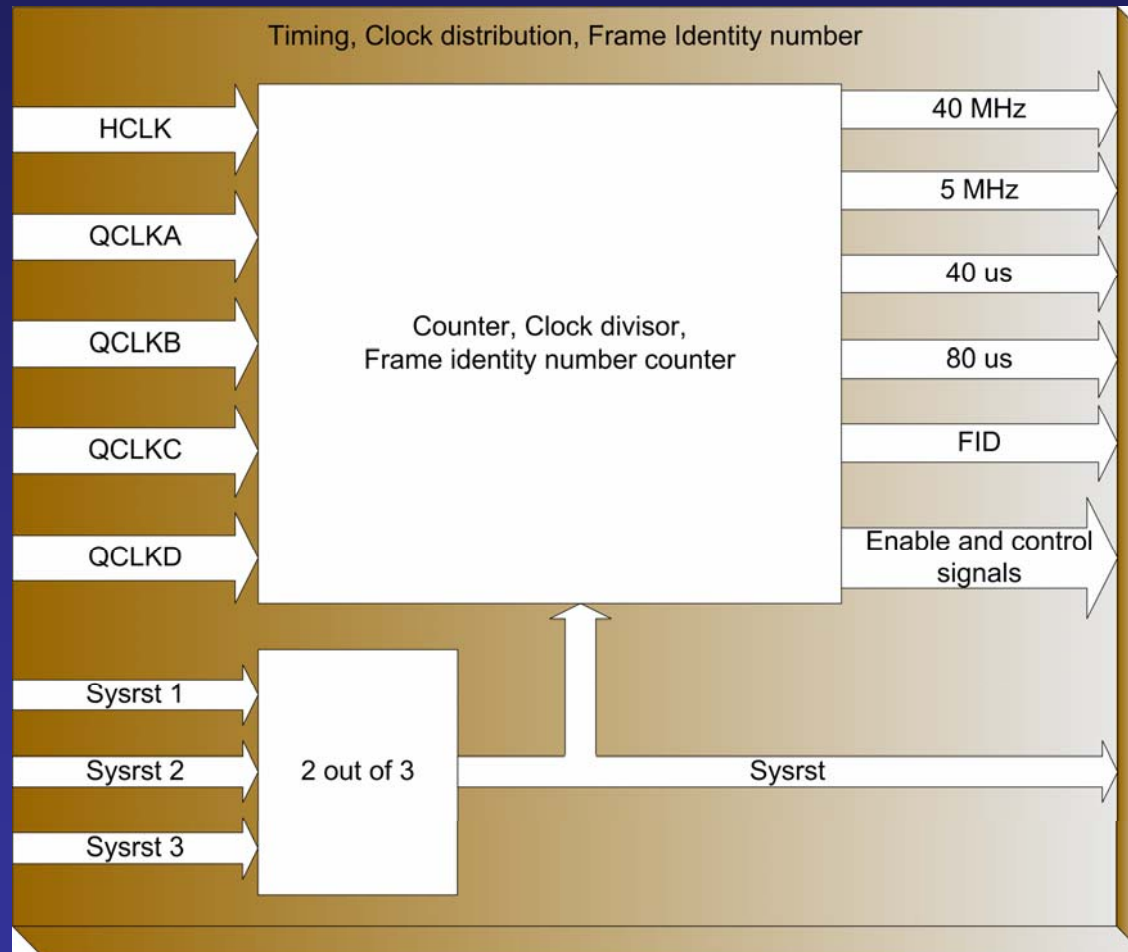


FPGA functional description



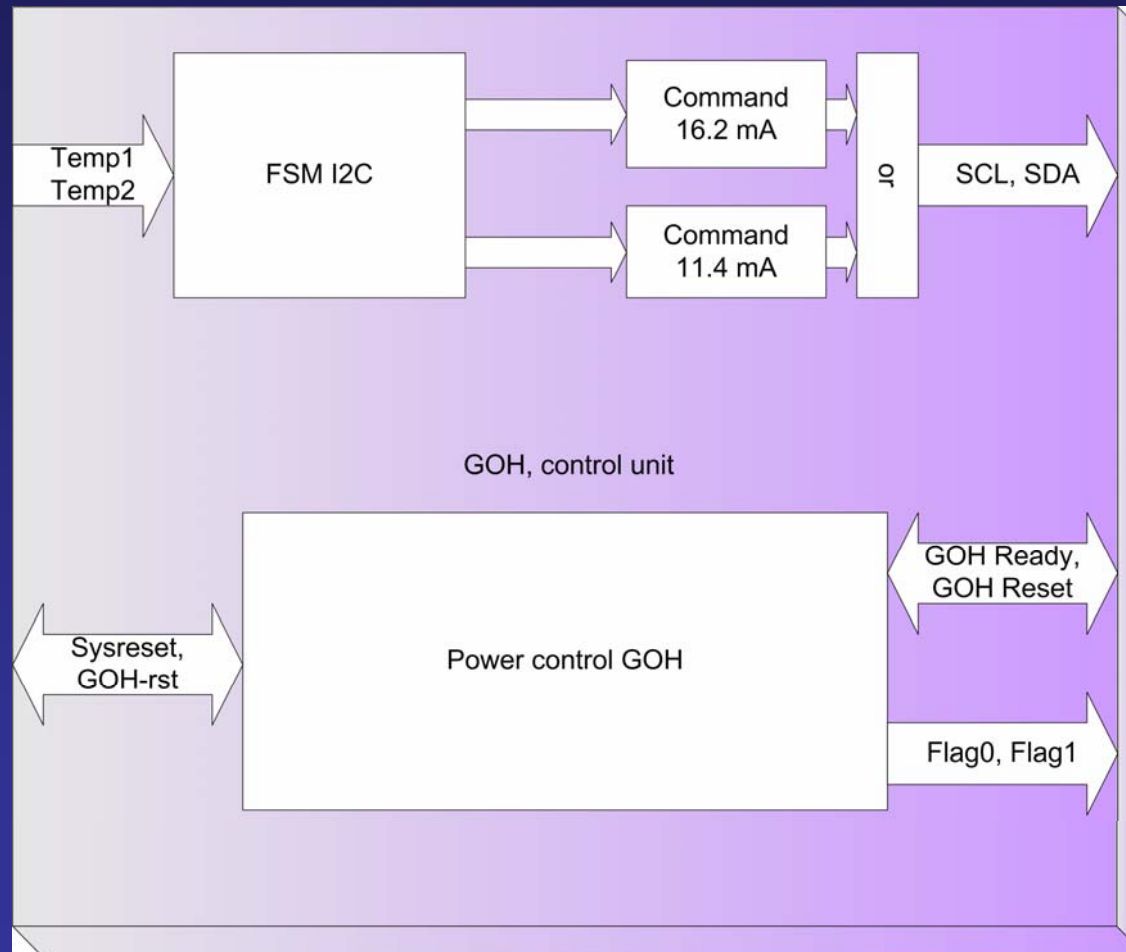


Functional description of FPGA



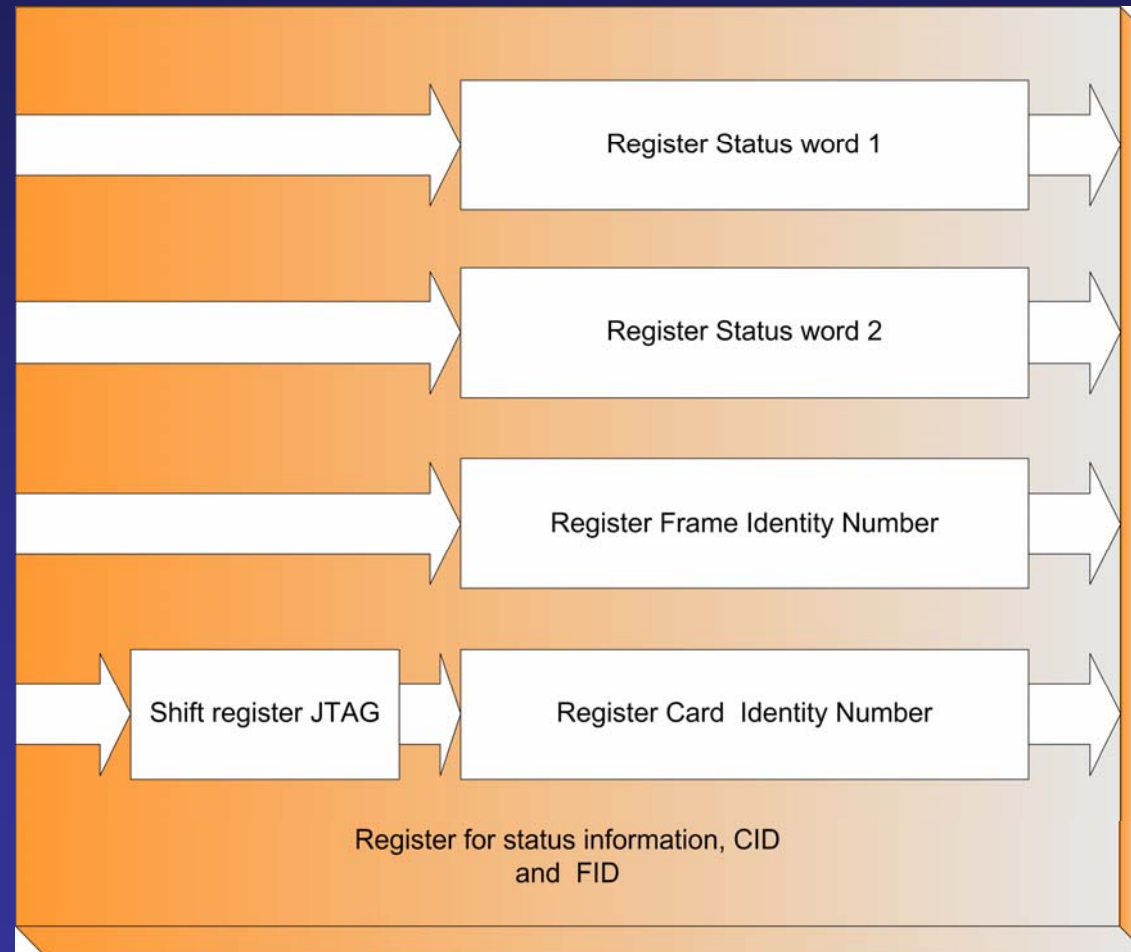


Functional description of FPGA





FPGA functional description





FPGA functional description



CID (card identity number)		
STATUS 1		
STATUS 2 (Level 1-8, CFC-ERR 1-8)		
Count 1	ADC 1	
ADC 1	Count 2	ADC 2
ADC 2	Count 3	
ADC 3	Count 4	
Count 4	ADC 4	
Count 5	ADC 5	
ADC 5	Count 6	ADC 6
ADC 6	Count 7	
ADC 7	Count 8	
Count 8	ADC8	
FID (frame identity number)		
DAC1	DAC2	
DAC3	DAC4	
DAC5	DAC6	
DAC7	DAC8	
CRC		
CRC		



FPGA functional description

